Futurrex, Inc.

12 CORK HILL ROAD FRANKLIN, NJ 07416 www.futurrex.com Tel: (973) 209-1563 Fax: (973) 209-1567 E-MAIL: info@futurrex.com

ZINC PHOSPHORUS DOPANT ZPDC2-2000

Description

ZPDC2-2000 is designed for zinc doping of III-V semiconductors. Application of ZPDC2-2000 enhances productivity of zinc doping through process simplification.

Properties

♦ Solids content (%)
 ♦ Principal solvent
 ♦ Appearance
 ♦ Coating characteristic

14-16

 n-butanol
 clear liquid
 very uniform,

striation free

Film thickness after 100°C oven bake for 5 minutes.

Coating spin speed, 40 s spin (rpm): (nm) 800 3800-4200 3000 1900-2100

◆ Guaranteed shelf life at 25°C storage (years)
 6 months

Process Application:

- 1. Application of ZPDC2-2000 on top of silicon nitride layer with open diffusion windows by spin coating of a substrate at a selected spin speed for 40 s.
- 2. Hotplate bake at 200°C for 180 s.
- 3. Oxygen plasma treatment of ZPDC2-2000 film for a duration of time sufficient to remove 4 µm thick layer of photoresist.
- 4. Deposition of 100 nm thick capping layer of silicon nitride.
- 5. Drive-in process with application of Rapid Thermal Annealing or furnace heating.
- 6. Removal of ZPDC2-2000 and silicon nitride films in HF/water 1:1.
- 7. Deposition of silicon nitride, followed by lithography and etching steps.